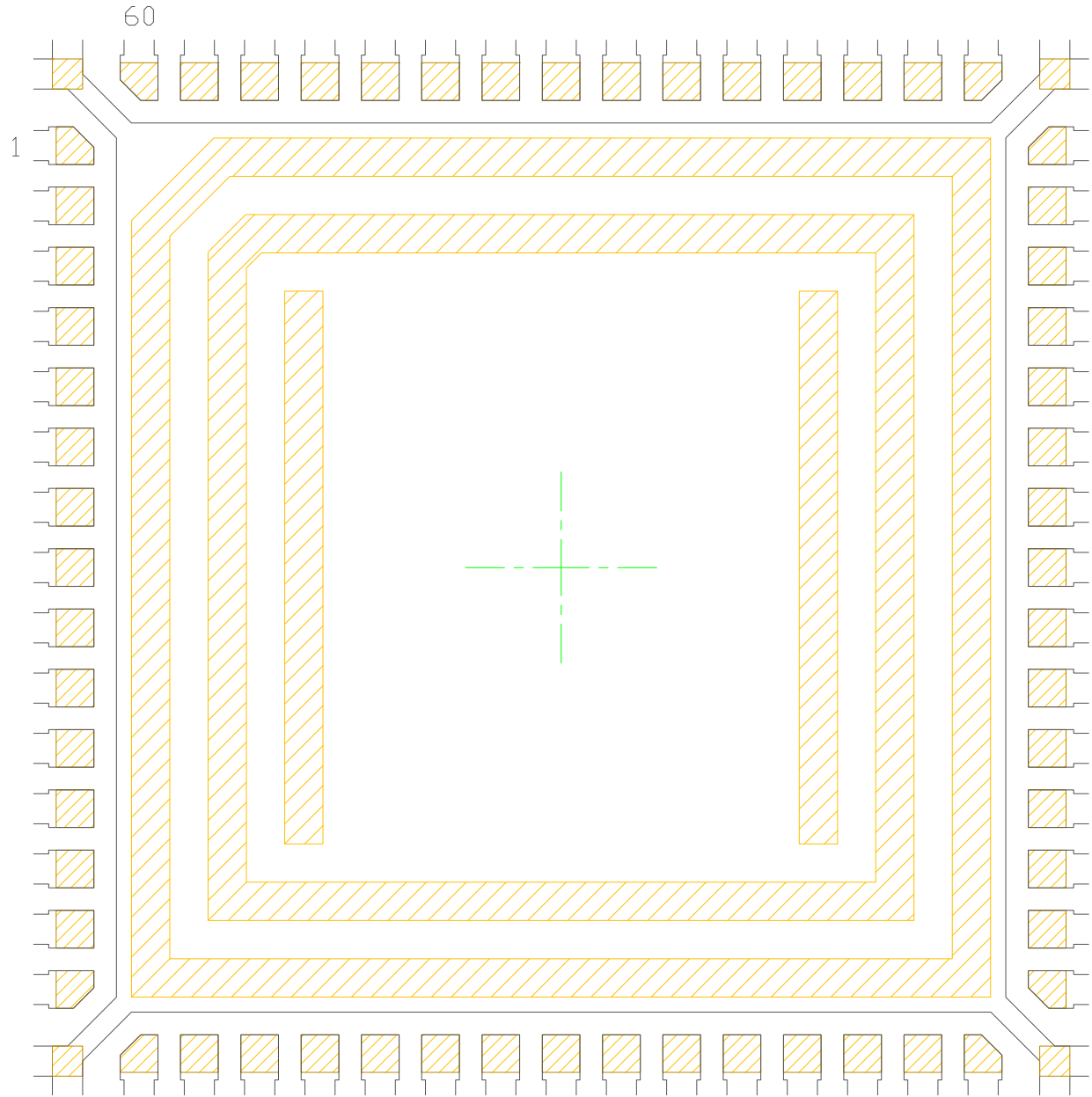



| REVISIONS | | |
|-----------|-----------------|-----------|
| REV | DESCRIPTION | DATE |
| A | INITIAL RELEASE | 4-28-2017 |



 NiPdAu PLATING

ALL INFORMATION CONTAINED HEREIN IS THE PROPERTY OF PROMEX, INC. AND IS CONSIDERED PROPRIETARY AND SUBJECT TO RETURN UPON DEMAND. ACCEPTANCE AND RETENTION HEREOF SIGNIFIES AGREEMENT BY THE RECIPIENT THAT THE INFORMATION WILL NOT BE DISCLOSED TO OTHERS NOR USED CONTRARY TO THE INTEREST OF PROMEX, INC. WITHOUT PRIOR WRITTEN PERMISSION.

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|-----------------------------|--------------------------------------|--|-------------------------------------|-----------------|
| CUSTOMER: xxxxx | DOCUMENT #: |  www.promex-ind.com | | |
| PROJECT NAME: xxxxx | DIE ATTACH PAD SIZE: 5.90 x 5.90 mm | | | |
| DIE SIZE, mm: xxxxx | EXPOSED PAD SIZE: 5.60 x 5.60 mm | TITLE QFN 60L 7x7 mm 0.40 PITCH BOND SHELL | | |
| DIE THICKNESS, um: xxxxx | DAP PLATING OPTION: 3x GROUND RING | LEADFRAME P/N: 235-00115 | | |
| BOND PAD PITCH, um: xxxxx | PLATING MATERIAL: NiPdAu | REV A | | |
| BOND PAD OPENING, um: xxxxx | LEADFRAME MATERIAL: C194 FH | | | |
| WIRE SIZE, um: xxxxx | LEADFRAME THICKNESS: 0.203±0.0075 mm | DO NOT SCALE | FILE NAME 60L-QFN-7X7-40P-BD.DWG | SHEET 1 OF 1 |